

SMA685xM Series

March, 2015

General Description

The SMA685xM series provides a highly-integrated solution by incorporating key components into one package – MOSFETs in a 3-phase full-bridge configuration, built-in protection functions such as UVLO (undervoltage lockout) and TD (thermal detection) circuits, pre-driver ICs with 7.5 V regulator output, and bootstrap diodes with limiting resistors.

The products are capable of detecting overcurrent through three shunt resistors. And their packages are fully-molded SIPs.

Applications

Include motor control for:

- Air conditioner fan
- Air purifier fan
- Washer-dryer fan

Features and Benefits

- Built-in bootstrap diodes with limiting resistors
- CMOS-compatible input (3.3 or 5 V)
- Built-in protection circuit for controlling power supply voltage drop (UVLO)
- Built-in overheat detection circuit (TD)
- Regulator output: 7.5 V, 35 mA
- Overcurrent detection enabled via three shunt resistors
- Small SIP (SMA, 24 pins)

Package

- Package Name: SMA
- Pin Pitch: 1.27 mm
- External Size: 31 × 10.2 × 4 mm

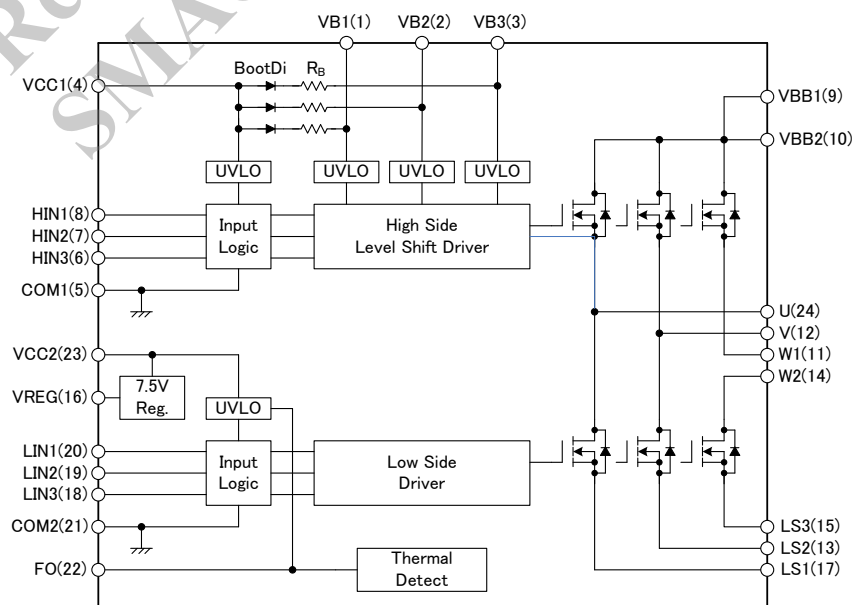


Not to scale

Product Specifications

Part Number	MOSFET Breakdown Voltage, V_{DDS} (V)	Output Current (Continuous), I_O (A)	MOSFET On-Resistance, $R_{DS(ON)}$ (Ω Max.)
SMA6852MZ	500	1.5	4.0
SMA6853MX	500	2.5	2.4
SMA6854MZ	600	1.5	3.5

Functional Block Diagram



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1. Scope

The specifications described in this document shall apply to the SMA685xM series, high-voltage 3-phase motor driver ICs.

2. Absolute Maximum Ratings, valid at $T_A = 25^\circ\text{C}$

Characteristics	Symbol	Remarks	Ratings	Unit
MOSFET Breakdown Voltage	V_{DSS}	SMA6852MZ $V_{CC} = 15\text{ V}$, $I_D = 100\text{ }\mu\text{A}$, $V_{IN} = 0\text{ V}$	500	V
		SMA6853MX $V_{CC} = 15\text{ V}$, $I_D = 100\text{ }\mu\text{A}$, $V_{IN} = 0\text{ V}$	500	V
		SMA6854MZ $V_{CC} = 15\text{ V}$, $I_D = 100\text{ }\mu\text{A}$, $V_{IN} = 0\text{ V}$	600	V
Logic Supply Voltage	V_{CC}	Between VCC and COM	20	V
Bootstrap Voltage	V_{BS}	Between VB and phase U, V, or W	20	V
Output Current (Continuous)	I_O	SMA6852MZ	1.5	A
		SMA6853MX	2.5	A
		SMA6854MZ	1.5	A
Output Current (Pulsed)	I_{OP}	SMA6852MZ $P_W \leq 100\text{ }\mu\text{s}$	2.25	A
		SMA6853MX $P_W \leq 100\text{ }\mu\text{s}$	3.75	A
		SMA6854MZ $P_W \leq 100\text{ }\mu\text{s}$	2.25	A
Output Current for Regulator	I_{REG}		35	mA
Input Voltage	V_{IN}	HIN and LIN pins	-0.5 to 7	V
Allowable Power Dissipation	P_D	$T_C = 25^\circ\text{C}$	28	W
Thermal Resistance (Junction-to-Case)	R_{j-c}	All elements operating	4.46	$^\circ\text{C/W}$
Thermal Resistance (Junction-to-Ambient)	R_{j-a}	All elements operating	31.25	$^\circ\text{C/W}$
Case Operating Temperature	$T_{C(OP)}$		-20 to 100	$^\circ\text{C}$
Junction Temperature	T_j		150	$^\circ\text{C}$
Storage Temperature	T_{stg}		-40 to 150	$^\circ\text{C}$

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3. Electrical Characteristics

3-1. Electrical Characteristics, valid at $T_a = 25^\circ\text{C}$, $V_{CC} = 15\text{ V}$

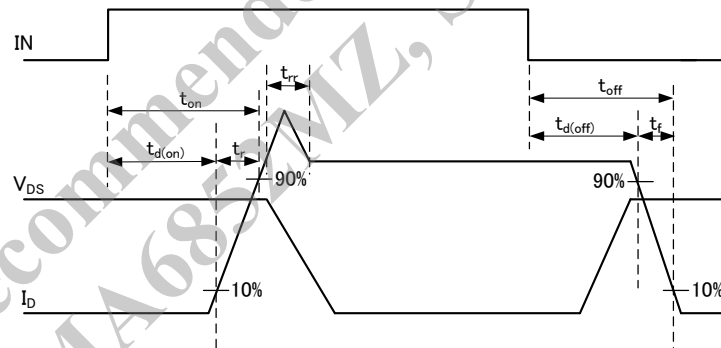
Characteristics	Symbol	Remarks	Ratings			Unit
			Min.	Typ.	Max.	
Logic Supply Current	I_{CC}	$I_{REG} = 0\text{ A}$	—	2.5	4	mA
Input Voltage	V_{IH}	Output ON	—	2.0	2.5	V
	V_{IL}	Output OFF	1.0	1.5	—	V
	V_{HYS}	Hysteresis	—	0.5	—	V
Input Current	I_{IH}	$V_{IN} = 5\text{ V}$	—	50	100	μA
	I_{IL}	$V_{IN} = 0\text{ V}$	—	—	2	μA
Undervoltage Lockout (Bootstrap)	V_{UVHL}	Between VB and U, V, or W	9.0	10.0	11.0	V
	V_{UVHH}	Between VB and U, V, or W	9.5	10.5	11.5	V
	V_{UVhys}	Between VB and U, V, or W; hysteresis	—	0.5	—	V
Undervoltage Lockout (Logic Supply)	V_{UVLL}	Between VCC and COM	10.0	11.0	12.0	V
	V_{UVLH}	Between VCC and COM	10.5	11.5	12.5	V
	V_{UVhys}	Between VCC and COM; hysteresis	—	0.5	—	V
FO Terminal Output Voltage	V_{FOL}		0	—	1.0	V
	V_{FOH}		4.0	—	5.5	V
Overheat Detection Threshold Temperature (Activation/Deactivation)	T_{DH}	$I_{REG} = 0\text{ mA}$, no heatsink	135	150	165	$^\circ\text{C}$
	T_{DL}	$I_{REG} = 0\text{ mA}$, no heatsink	105	120	135	$^\circ\text{C}$
	T_{DHYS}	$I_{REG} = 0\text{ mA}$, no heatsink, hysteresis	—	30	—	$^\circ\text{C}$
Output Voltage for Regulator	V_{REG}	$I_{REG} = 0\text{ to }35\text{ mA}$	6.75	7.5	8.25	V
Bootstrap Diode Leakage Current	I_{LBD}	SMA6852MZ $V_R = 500\text{ V}$	—	—	10	μA
		SMA6853MX $V_R = 500\text{ V}$	—	—	10	μA
		SMA6854MZ $V_R = 600\text{ V}$	—	—	10	μA
Bootstrap Diode Forward Voltage	V_{FB}	$I_{FB} = 0.15\text{ A}$	—	1.1	1.3	V
Bootstrap Diode Series Resistor	R_B	SMA6852MZ	17.6	22.0	26.4	Ω
		SMA6853MX	17.6	22.0	26.4	Ω
		SMA6854MZ	48	60	72	Ω
MOSFET Breakdown Voltage	I_{DSS}	SMA6852MZ $V_{DS} = 500\text{ V}$, $V_{IN} = 0\text{ V}$	—	—	100	μA
		SMA6853MX $V_{DS} = 500\text{ V}$, $V_{IN} = 0\text{ V}$	—	—	100	μA
		SMA6854MZ $V_{DS} = 600\text{ V}$, $V_{IN} = 0\text{ V}$	—	—	100	μA
MOSFET On-Resistance	$R_{DS(ON)}$	SMA6852MZ $I_D = 0.75\text{ A}$, $V_{IN} = 5\text{ V}$	—	3.6	4.0	Ω
		SMA6853MX $I_D = 1.25\text{ A}$, $V_{IN} = 5\text{ V}$	—	2.0	2.4	Ω
		SMA6854MZ $I_D = 0.75\text{ A}$, $V_{IN} = 5\text{ V}$	—	3.0	3.5	Ω
MOSFET Diode Forward Voltage	V_{SD}	SMA6852MZ $I_{SD} = 0.75\text{ A}$, $V_{IN} = 0\text{ V}$	—	1.1	1.5	V
		SMA6853MX $I_{SD} = 1.25\text{ A}$, $V_{IN} = 0\text{ V}$	—	1.1	1.5	V
		SMA6854MZ $I_{SD} = 0.75\text{ A}$, $V_{IN} = 0\text{ V}$	—	1.1	1.5	V

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3-1. Electrical Characteristics, valid at $T_a = 25^\circ\text{C}$ (continued)

Characteristics	Symbol	Remarks		Ratings						Unit
				H-Side			L-Side			
				Min.	Typ.	Max.	Min.	Typ.	Max.	
Switching Time	t _{d(on)}	SMA6852MZ	V _{DC} = 300 V, V _{CC} = 15 V, I _D = 1.5 A, V _{IN} = 0→5 V or 5→0 V, T _j = 25°C, inductive load	—	530	—	—	530	—	ns
	t _r			—	95	—	—	95	—	ns
	t _{rr}			—	130	—	—	120	—	ns
	t _{d(off)}			—	385	—	—	445	—	ns
	t _f			—	40	—	—	30	—	ns
	t _{d(on)}	SMA6853MX	V _{DC} = 300 V, V _{CC} = 15 V, I _D = 2.5 A, V _{IN} = 0→5 V or 5→0 V, T _j = 25°C, inductive load	—	650	—	—	700	—	ns
	t _r			—	100	—	—	100	—	ns
	t _{rr}			—	150	—	—	150	—	ns
	t _{d(off)}			—	520	—	—	580	—	ns
	t _f			—	50	—	—	40	—	ns
	t _{d(on)}	SMA6854MZ	V _{DC} = 300 V, V _{CC} = 15 V, I _D = 1.5 A, V _{IN} = 0→5 V or 5→0 V, T _j = 25°C, inductive load	—	530	—	—	530	—	ns
	t _r			—	55	—	—	60	—	ns
	t _{rr}			—	125	—	—	125	—	ns
	t _{d(off)}			—	510	—	—	540	—	ns
	t _f			—	50	—	—	55	—	ns



Switching Characteristics Definitions

3-2. Recommended Operating Conditions

Characteristics	Symbol	Remarks		Ratings			Unit
				Min.	Typ.	Max.	
Main Supply Voltage	V _{DC}	SMA6852MZ	Between VBB and LS	—	300	400	V
		SMA6853MX	Between VBB and LS	—	300	400	V
		SMA6854MZ	Between VBB and LS	—	300	450	V
Logic Supply Voltage	V _{CC}	Between VCC and COM		13.5	—	16.5	V
Minimum Input Pulse Width	t _{INmin(on)}			0.5	—	—	μs
	t _{INmin(off)}			0.5	—	—	μs
Dead Time	t _{dead}			1.5	—	—	μs

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3-3. Truth Table

Mode	HIN	LIN	High-Side MOSFET	Low-Side MOSFET
Normal	L	L	OFF	OFF
	H	L	ON	OFF
	L	H	OFF	ON
	H	H	ON	ON
Thermal Detection (TD)	L	L	OFF	OFF
	H	L	ON	OFF
	L	H	OFF	ON
	H	H	ON	ON
UVLO (VCC)	L	L	OFF	OFF
	H	L	OFF	OFF
	L	H	OFF	OFF
	H	H	OFF	OFF
UVLO (VB)	L	L	OFF	OFF
	H	L	OFF	OFF
	L	H	OFF	ON
	H	H	OFF	ON

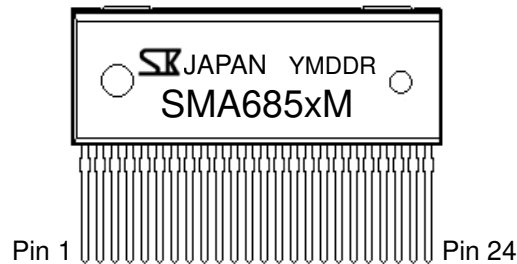
NOTES:

- An arm short-circuit may occur when inputs on the HIN and LIN pins for the same phase are all logic high. Therefore, extra attention should be paid to prevent a condition in which the pins for the same phase are fully ON at once.
- A MOSFET in a V_{CC} UVLO state gets re-activated when an input signal is detected at a certain logic level (level triggering), while a MOSFET in a V_B UVLO state resumes its operation at a point where an input signal transits from one state to another (edge triggering).

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4. Pin-Out Diagram



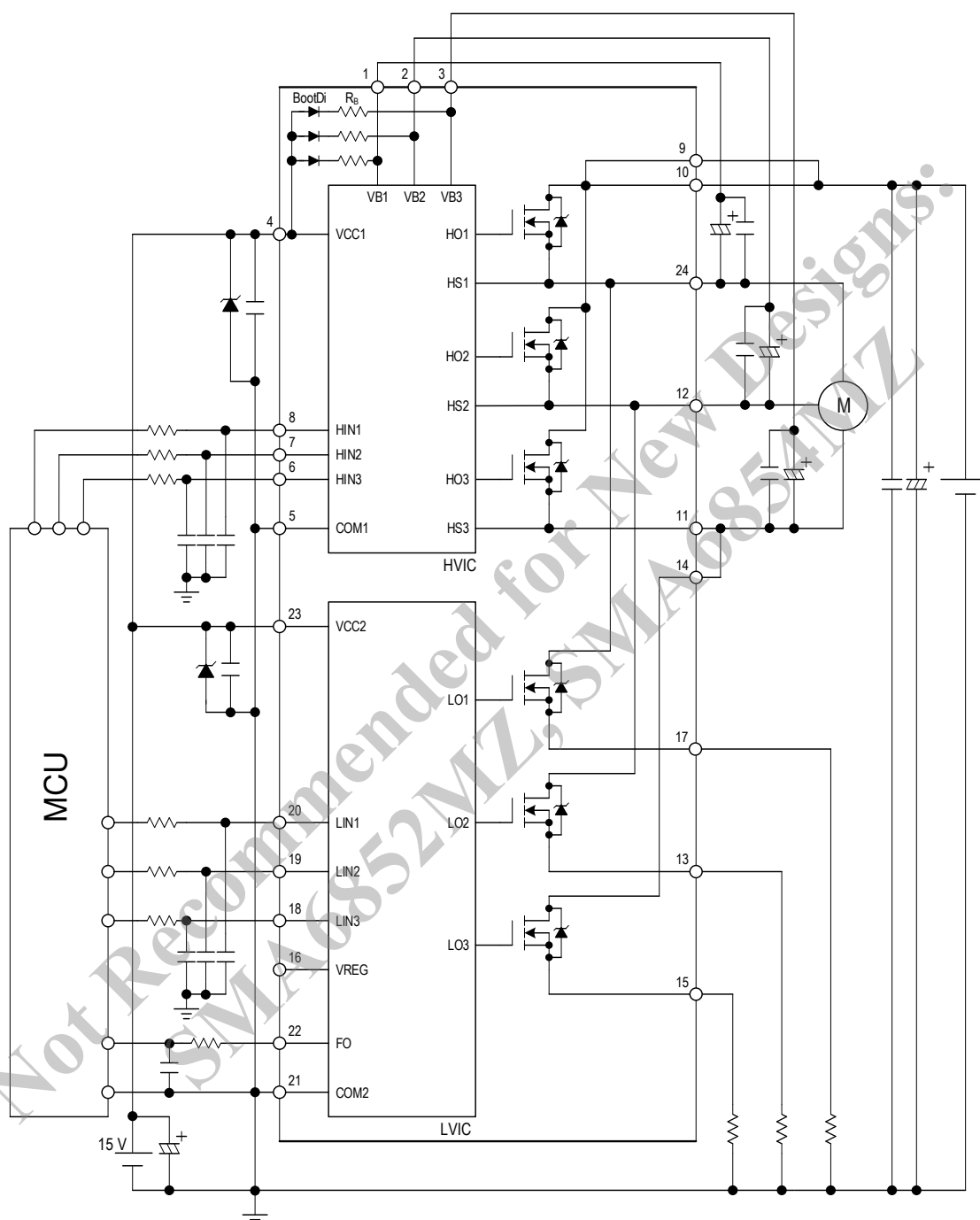
Terminal List Table

Pin Number	Pin Name	Functions	I/O
1	VB1	High-side bootstrap (phase U)	—
2	VB2	High-side bootstrap (phase V)	—
3	VB3	High-side bootstrap (phase W)	—
4	VCC1	High-side logic supply voltage	—
5	COM1	High-side logic GND	—
6	HIN3	High-side input (phase W)	Input
7	HIN2	High-side input (phase V)	Input
8	HIN1	High-side input (phase U)	Input
9	VBB1	Main supply voltage 1 (connected to VBB2 externally)	—
10	VBB2	Main supply voltage 2 (connected to VBB1 externally)	—
11	W1	Phase W output (connected to W2 externally)	—
12	V	Phase V output	—
13	LS2	Low-side source (phase V)	—
14	W2	Phase W output (connected to W1 externally)	—
15	LS3	Low-side source (phase W)	—
16	VREG	Internal regulator output	Output
17	LS1	Low-side source (phase U)	—
18	LIN3	Low-side input (phase W)	Input
19	LIN2	Low-side input (phase V)	Input
20	LIN1	Low-side input (phase U)	Input
21	COM2	Low-side logic GND	—
22	FO	Error output	Output
23	VCC2	Low-side logic supply voltage	—
24	U	Phase U output	—

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5. Application Example



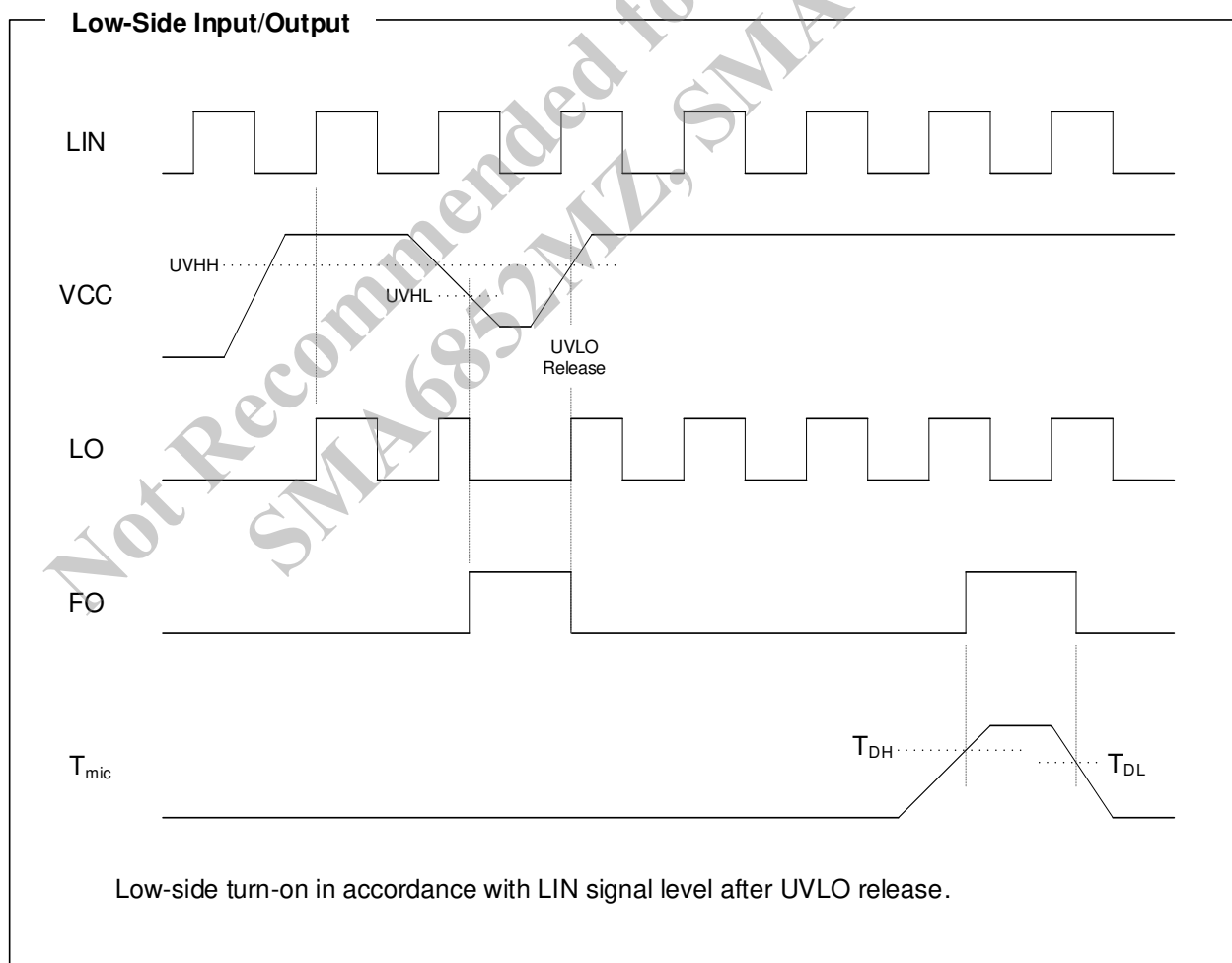
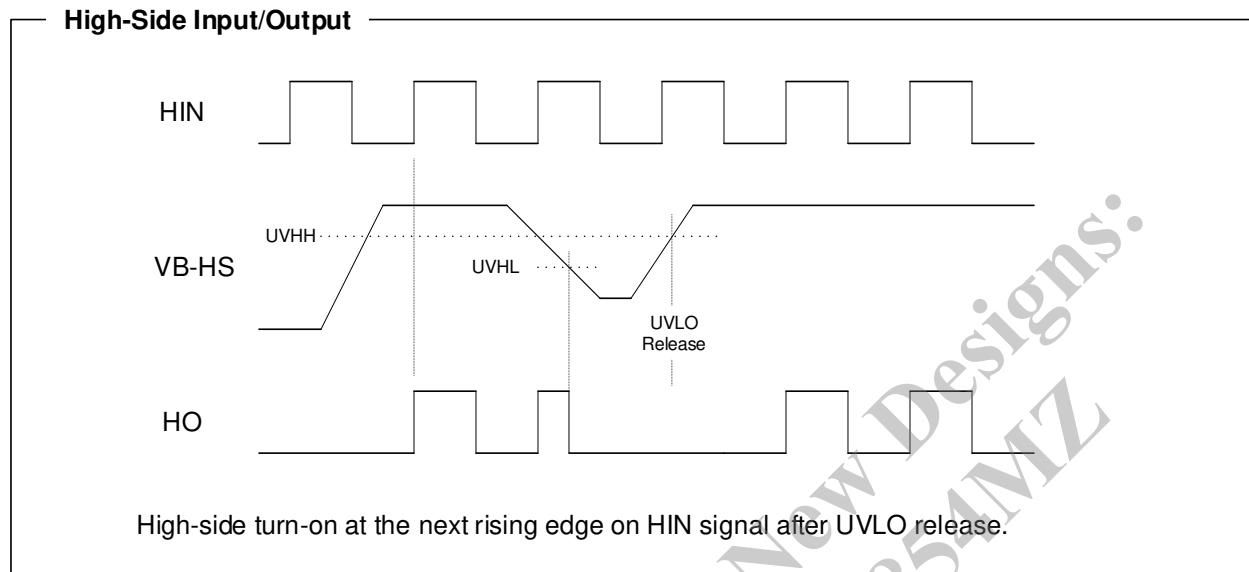
NOTES:

- All of the input pins are connected to GND with internal pull-down resistors rated at 100 kΩ. However, an external pull-down resistor may be required to secure stable condition of the inputs if high impedance conditions are applied to them.
- The external electrolytic capacitors should be placed as close to the IC as possible, in order to avoid malfunctions from external noise interference. Put a ceramic capacitor in parallel with the electrolytic capacitor if further reduction of noise susceptibility is necessary.

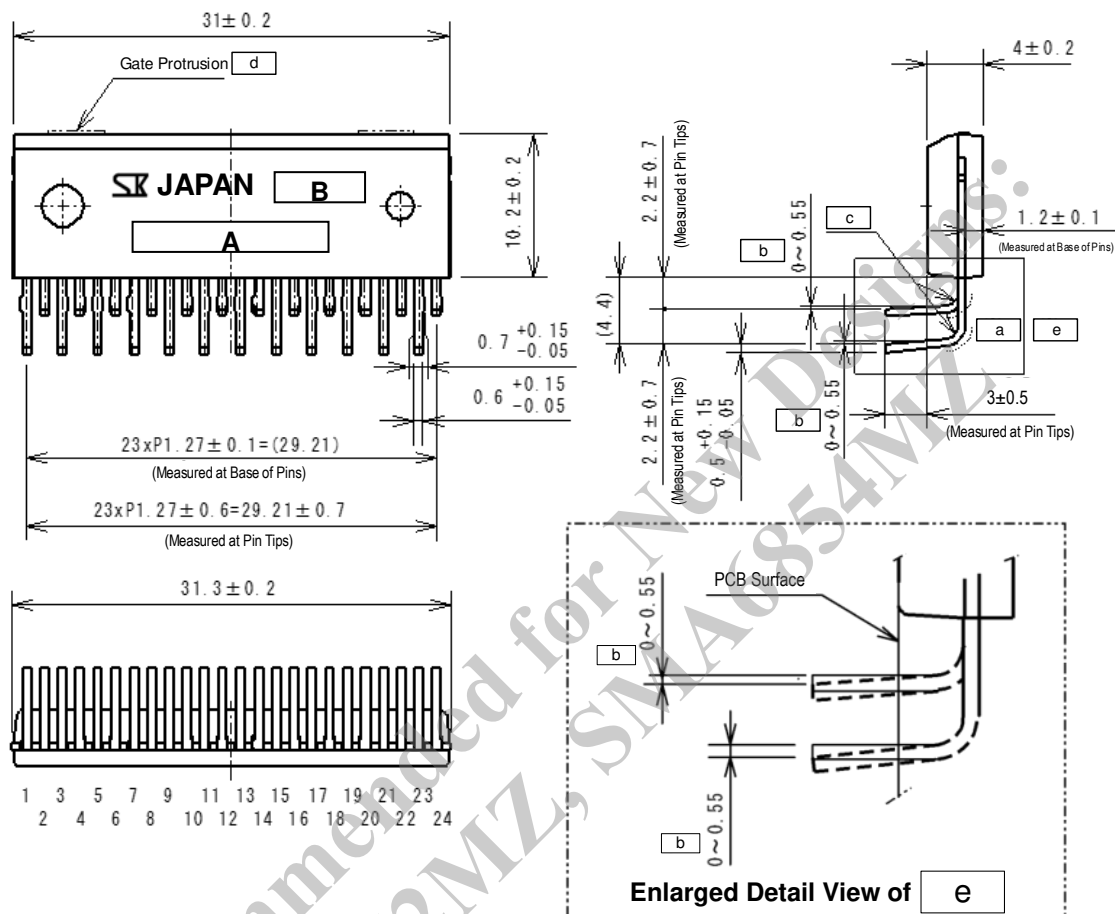
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6. Timing Diagrams for Protection Operations



7-1. Leadform 2451 (Dimensions in Millimeters)



- **a** depicts the intentionally-curved part of a pin whose plated surface may easily be cracked and/or peeled off. Note that this kind of damaged surface does NOT indicate negative effects on terminal flexural toughness or any other reliability characteristics.
- **b** represents terminal curvature exaggerated for illustration purposes, not actual states of being bent or curved.
- **c** shows pins with a minimum inside radius (R) of 0.65 mm.
- **d** describes the area(s) where either one or two gate protrusions up to 0.3 mm high will appear on the package surface, drawn with dashed double-dotted lines. (The number of gate protrusions varies depending on the package mold type used.)

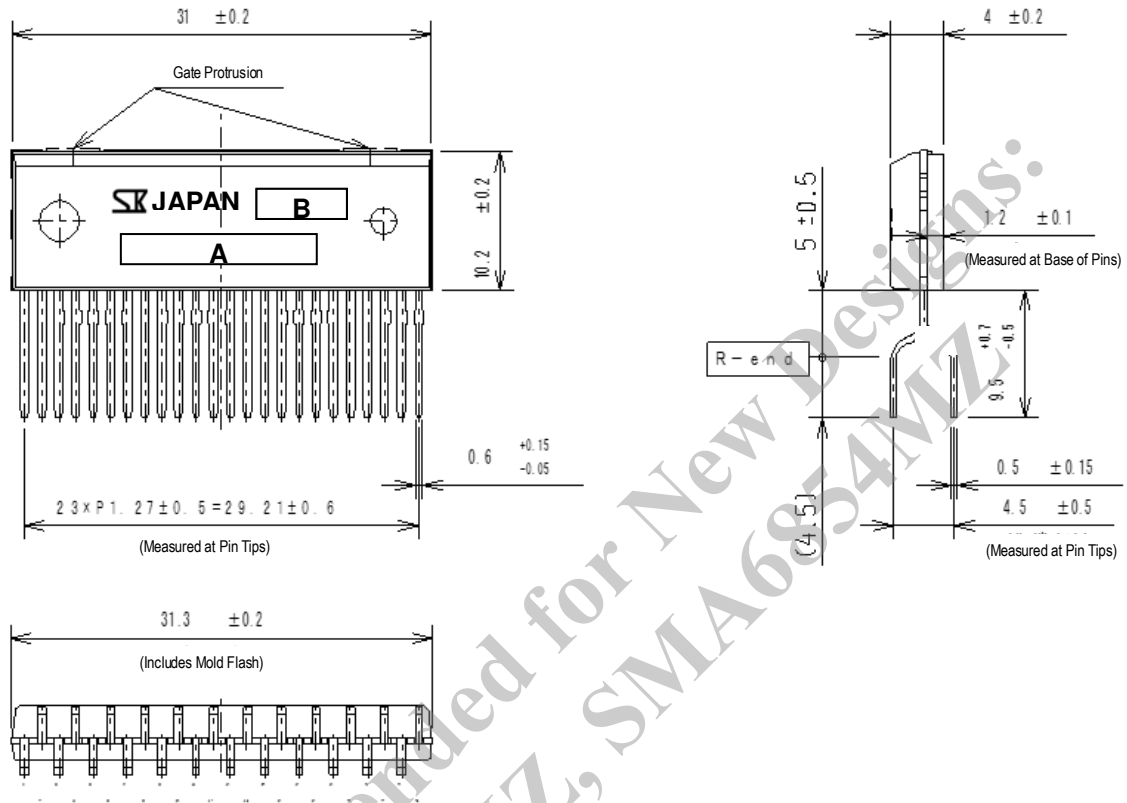
A. Part number: *SMA685xMX/MZ*
B. Lot number: *YMDDR*

- Y is the last digit of the year of manufacture
- M is the month of the year manufactured (1 to 9, O, N, or D)
- DD is the day of the month manufactured (01 to 31)
- R is the Sanken control number

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7-2. Leadform 2452 (Dimensions in Millimeters)



NOTE: Either one or two gate protrusions up to 0.3 mm high will appear on the package surface, as drawn with dashed double-dotted lines in the illustration above. (The number of gate protrusions varies depending on the package mold type used.)

■ Branding Codes

A. Part number: SMA685xMX/MZ

B. Lot number: YMDDR

- Y is the last digit of the year of manufacture
- M is the month of the year manufactured (1 to 9, O, N, or D)
- DD is the day of the month manufactured (01 to 31)
- R is the Sanken control number

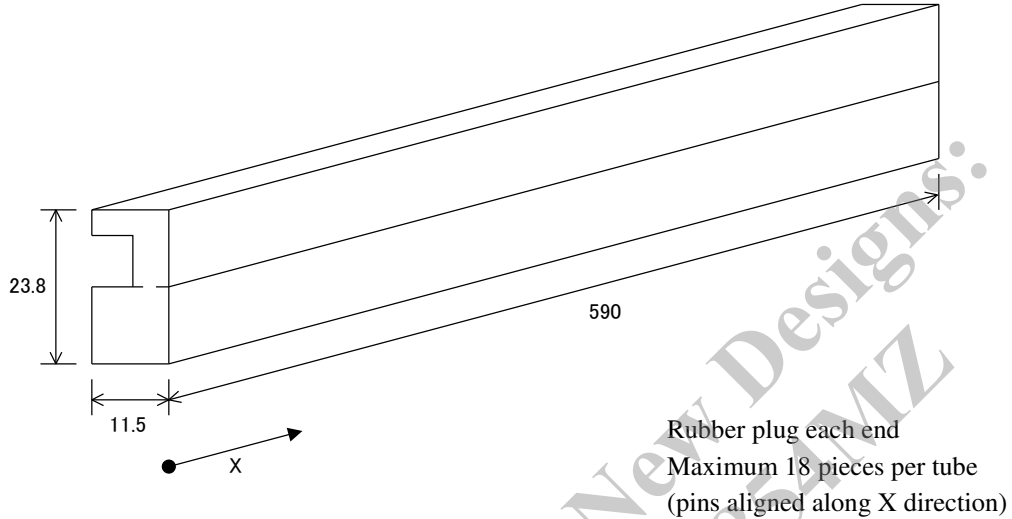
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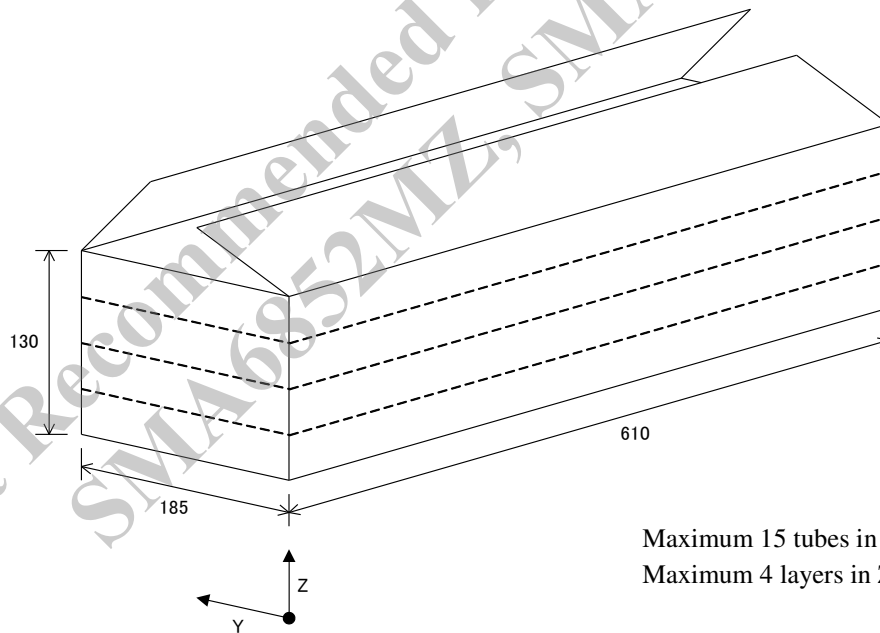
8. Packing Specifications

8-1. Leadform 2451 (Dimensions in Millimeters)

- Tube Type: SCM-C



- Corrugated Shipping Carton



Maximum 15 tubes in Y direction
Maximum 4 layers in Z direction

Maximum pieces per carton:

18 pieces per tube

15 tubes per layer

× 4 layers of tubes

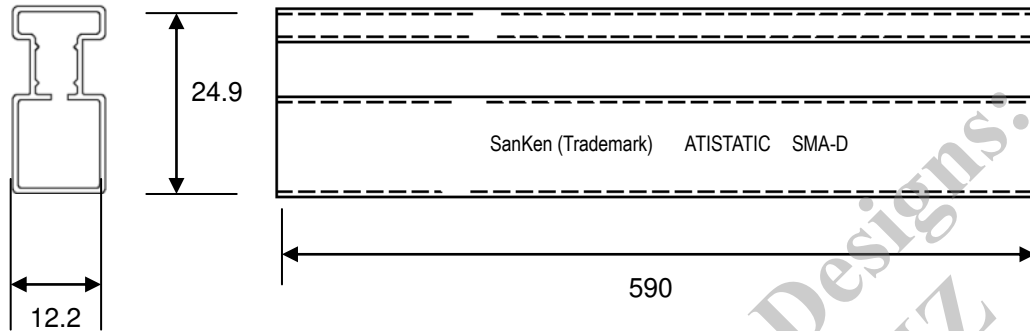
1080 pieces per carton

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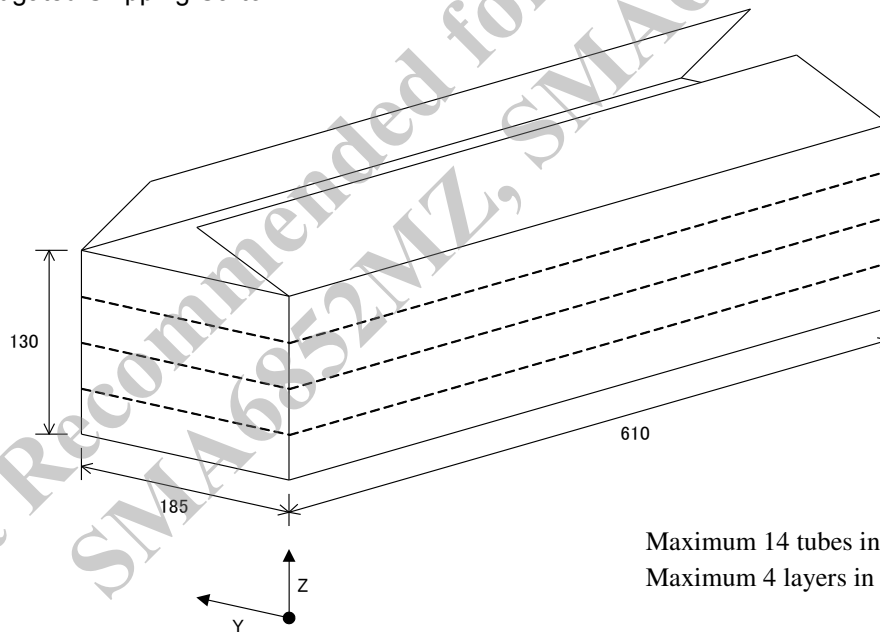
8-2. Leadform 2452 (Dimensions in Millimeters)

■ Tube Type: SMA-D



Rubber plug each end
Maximum 18 pieces per tube
(pins aligned along X direction)

■ Corrugated Shipping Carton



Maximum 14 tubes in Y direction
Maximum 4 layers in Z direction

Maximum pieces per carton:

18 pieces per tube

14 tubes per layer

$\times$ 4 layers of tubes

1008 pieces per carton

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